

DIGITRON SEMICONDUCTORS

3N209-3N210

N-CANNEL DUAL GATE MOS FIELD EFFECT TRANSISTORS

MAXIMUM RATINGS

| Rating | Symbol | Value | | Unit |
|---------------------------------------------------------------------------------------|--------------------------------------------------|------------------------|-------------|----------------------------|
| Drain – source voltage | V_{DS} | 25 | | Vdc |
| Drain gate voltage | V_{DG1} V_{DG2} | 30 | | Vdc |
| Gate current | I_{G1R} I_{G1F} I_{G2R} I_{G2F} | -10 10 -10 10 | | mAdc |
| Drain current – continuous | I_D | 30 | | mAdc |
| Total power dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 3N209 | 3N210 | mW mW/ $^\circ\text{C}$ |
| | | 300 1.71 | 350 2.80 | |
| Storage channel temperature range | T_{stg} | -65 to 200 | -65 to 175 | $^\circ\text{C}$ |
| Operating channel temperature | $T_{channel}$ | 200 | 150 | $^\circ\text{C}$ |
| Lead temperature, 1/16" from seated surface for 10 s | | 260 | | $^\circ\text{C}$ |

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|--------|--------|------------|-------------------------|
| OFF CHARACTERISTICS | | | | | |
| Drain source breakdown voltage ($I_D = 10\mu\text{Adc}$, $V_{G1S} = -4.0\text{Vdc}$, $V_{G2S} = 4.0\text{Vdc}$) | $V_{(BR)DS}$ | 25 | - | - | Vdc |
| Gate 1 – source forward breakdown voltage ($I_{G1} = 10\text{mAdc}$, $V_{G2S} = V_{DS} = 0$) | $V_{(BR)G1SSF}$ | 7.0 | - | 22 | Vdc |
| Gate 1 – source reverse breakdown voltage ($I_{G1} = -10\text{mAdc}$, $V_{G2S} = V_{DS} = 0$) | $V_{(BR)G1SSR}$ | 7.0 | - | -22 | Vdc |
| Gate 2 – source forward breakdown voltage ($I_{G2} = 10\text{mAdc}$, $V_{G1S} = V_{DS} = 0$) | $V_{(BR)G2SSF}$ | 7.0 | - | 22 | Vdc |
| Gate 2 – source reverse breakdown voltage ($I_{G2} = -10\text{mAdc}$, $V_{G1S} = V_{DS} = 0$) | $V_{(BR)G2SSR}$ | -7.0 | - | -22 | Vdc |
| Gate 1 – source cutoff voltage ($V_{DS} = 15\text{Vdc}$, $V_{G2S} = 4.0\text{Vdc}$, $I_D = 50\mu\text{Adc}$) | $V_{G1S(off)}$ | -0.1 | - | -4.0 | Vdc |
| Gate 2 – source cutoff voltage ($V_{DS} = 15\text{Vdc}$, $V_{G1S} = 0\text{Vdc}$, $I_D = 50\mu\text{Adc}$) | $V_{G2S(off)}$ | -0.1 | - | -4.0 | Vdc |
| Gate 1 – terminal forward current ($V_{G1S} = 6.0\text{Vdc}$, $V_{G2S} = V_{DS} = 0$) | I_{G1SSF} | - | - | 20 | nAdc |
| Gate 1 – terminal reverse current ($V_{G1S} = -6.0\text{Vdc}$, $V_{G2S} = V_{DS} = 0$) ($V_{G1S} = -6.0\text{Vdc}$, $V_{G2S} = V_{DS} = 0$, $T_A = 150^\circ\text{C}$) | I_{G1SSR} | - - | - - | -20 -10 | nAdc μAdc |
| Gate 2 – terminal forward current ($V_{G2S} = 6.0\text{Vdc}$, $V_{G1S} = V_{DS} = 0$) | I_{G2SSF} | - | - | 20 | nAdc |
| Gate 2 – terminal reverse current ($V_{G2S} = -6.0\text{Vdc}$, $V_{G1S} = V_{DS} = 0$) ($V_{G2S} = -6.0\text{Vdc}$, $V_{G1S} = V_{DS} = 0$, $T_A = 150^\circ\text{C}$) | I_{G2SSR} | - - | - - | -20 -10 | nAdc μAdc |
| ON CHARACTERISTICS | | | | | |
| Gate 1 – zero voltage drain current ($V_{DS} = 15\text{Vdc}$, $V_{G1S} = 0$, $V_{G2S} = 4.0\text{Vdc}$) | I_{DSS} | 5.0 | - | 30 | mAdc |

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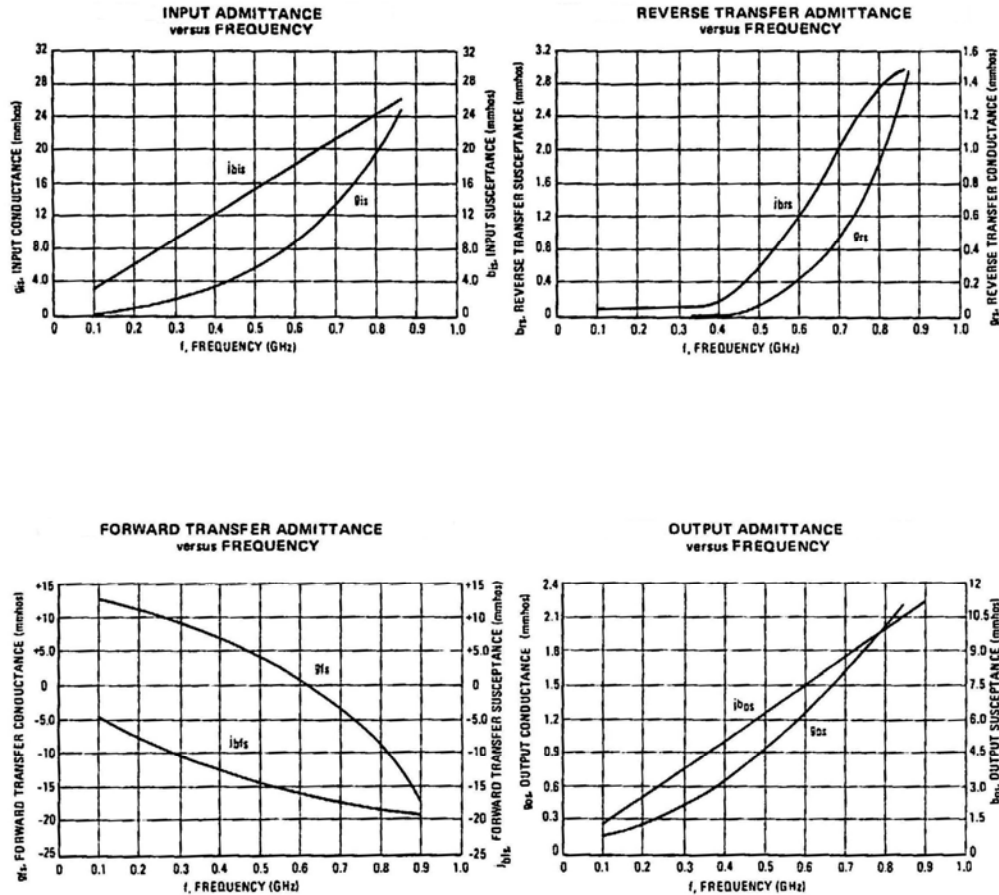
N-CANNEL DUAL GATE MOS FIELD EFFECT TRANSISTORS

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--------------------------------------------------------------------------------------------------------------------------------------------------|-----------|-------|-------|-------|-------|
| SMALL SIGNAL CHARACTERISTICS | | | | | |
| Forward transfer admittance ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$, $I_D = 10\text{mAdc}$, $f = 1.0\text{kHz}$) | Y_{fs} | 10 | 13 | 20 | mmhos |
| Input capacitance ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$, $I_D \geq 5.0\text{mAdc}$, $f = 1.0\text{MHz}$) | C_{iss} | - | 4.5 | 7.0 | pF |
| Reverse transfer capacitance ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$, $I_D \geq 5.0\text{mAdc}$, $f = 1.0\text{MHz}$) | C_{rss} | 0.005 | 0.023 | 0.030 | pF |
| Output capacitance ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$, $I_D \geq 5.0\text{mAdc}$, $f = 1.0\text{MHz}$) | C_{oss} | 0.5 | 2.0 | 4.0 | pF |
| Common source noise figure ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$, $I_D \geq 10\text{mAdc}$, $f = 500\text{MHz}$) | NF | - | 4.5 | 6.0 | dB |
| Common source power gain ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$, $I_D \geq 10\text{mAdc}$, $f = 500\text{MHz}$) | G_{ps} | 10 | 13 | 20 | dB |
| Bandwidth ($V_{DS} = 15\text{Vdc}$, $V_{GS2} = 4.0\text{Vdc}$; $I_D = 10\text{mAdc}$, $f = 500\text{MHz}$) | BW | 7.0 | - | 17 | MHz |

TYPICAL COMMON-SOURCE ADMITTANCE PARAMETERS

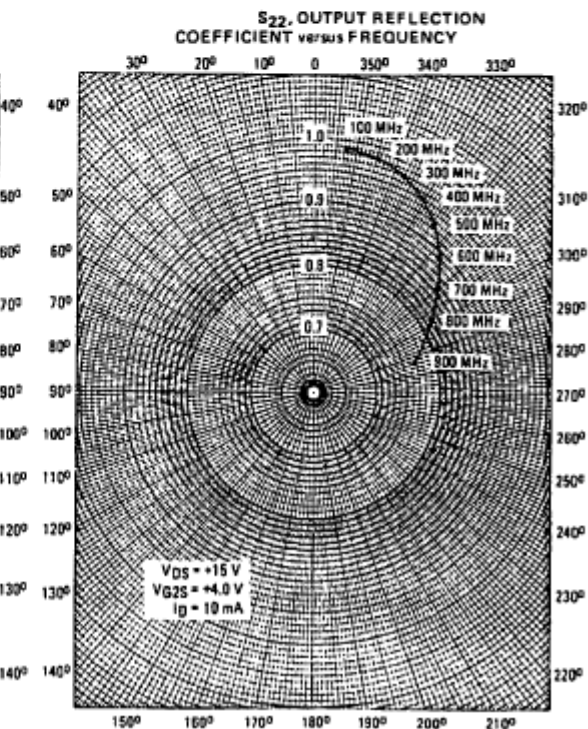
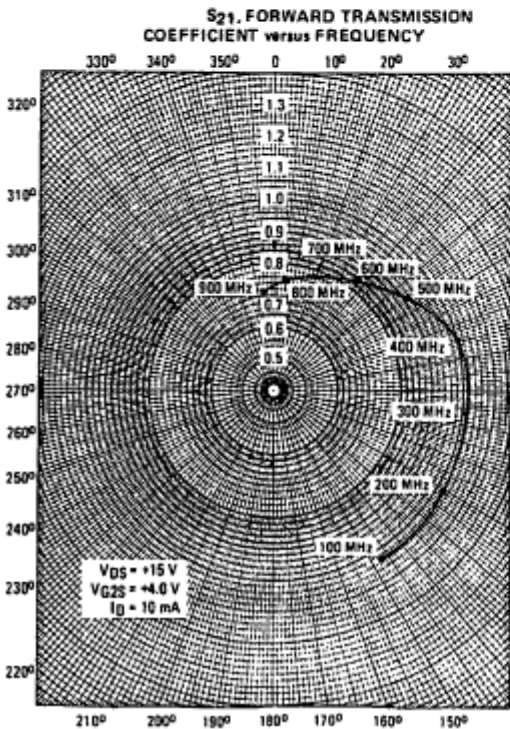
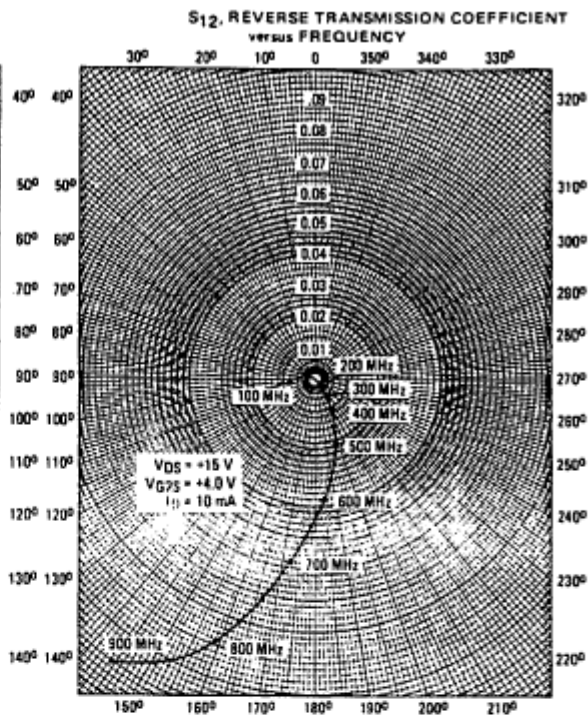
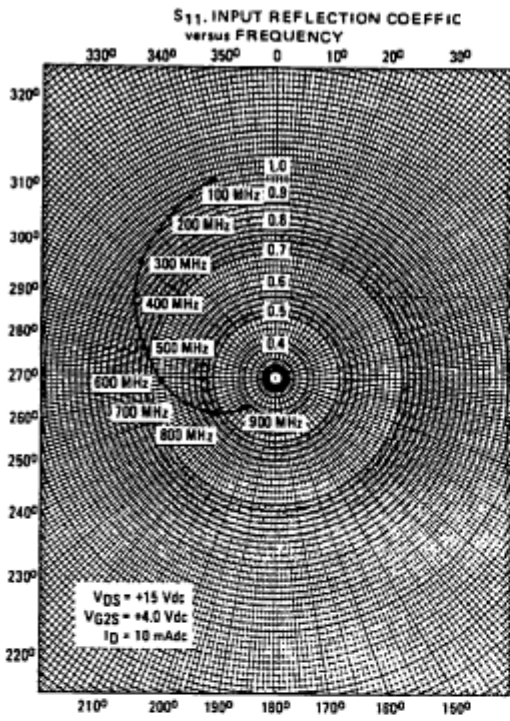
($V_{DS} = 15\text{ Vdc}$, $V_{GS2} = 4.0\text{ Vdc}$, $I_D = 10\text{ mAdc}$)



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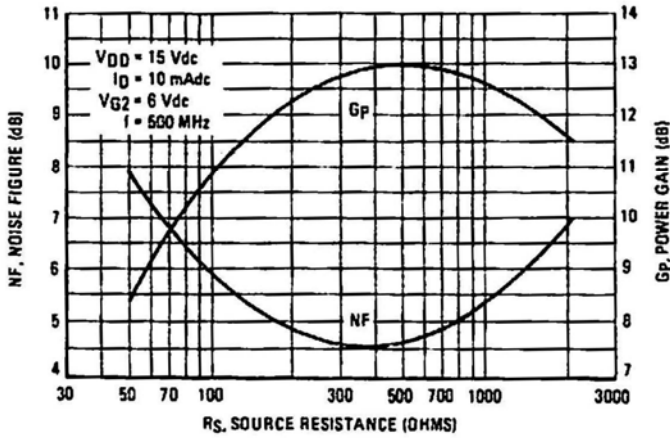


DIGITRON SEMICONDUCTORS

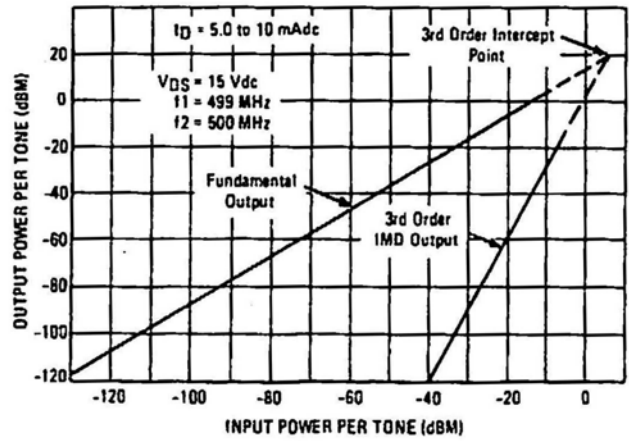
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N-CHANNEL DUAL GATE MOS FIELD EFFECT TRANSISTORS

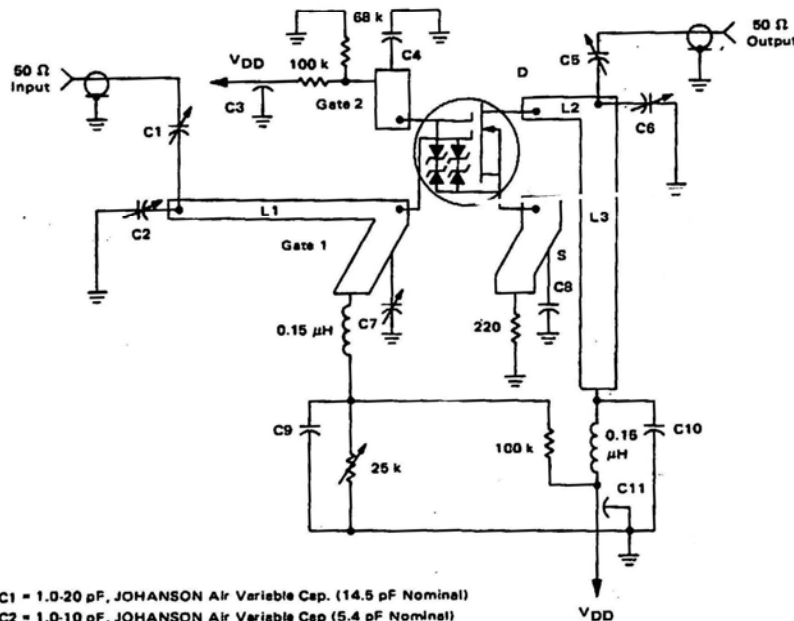
POWER GAIN AND NOISE FIGURE versus SOURCE RESISTANCE



THIRD ORDER INTERMODULATION DISTORTION



TEST CIRCUIT FOR POWER GAIN, NOISE FIGURE AND THIRD ORDER INTERMODULATION DISTORTION

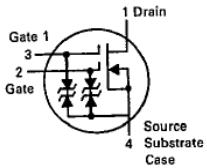


- C1 = 1.0-20 pF, JOHANSON Air Variable Cap. (14.5 pF Nominal)
- C2 = 1.0-10 pF, JOHANSON Air Variable Cap. (5.4 pF Nominal)
- C3, C11 = 470 pF, Low Inductance Feedthru Cap.
- C4, C8, C9, C10 = 250 pF, Low Inductance, UNDERWOOD Cap. (J-101)
- C5 = 0.4-6.0 pF, JOHANSON Air Variable Cap. (0.92 pF Nominal)
- C6 = 1.0-10 pF, JOHANSON Air Variable Cap. (5.9 pF Nominal)
- C7 = 1.0-10 pF, JOHANSON Air Variable Cap. (3.0 pF Nominal)
- L1 = 2.52 x 0.1 inches } On 2 sided glass Teflon, 1 oz. copper clad, 1/16"
- L2 = 0.4 x 0.1 inches } $\epsilon_R = 2.55$
- L3 = 1.23 x 0.2 inches }

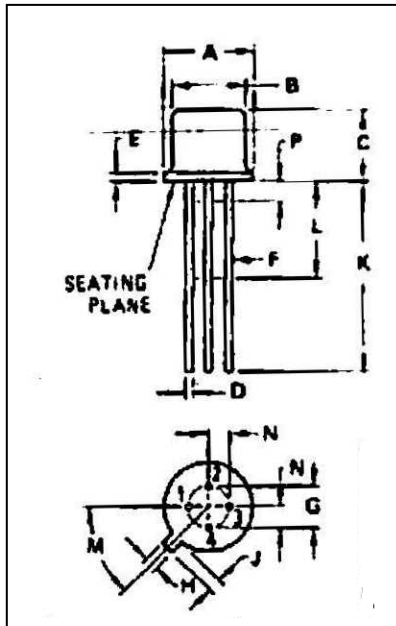
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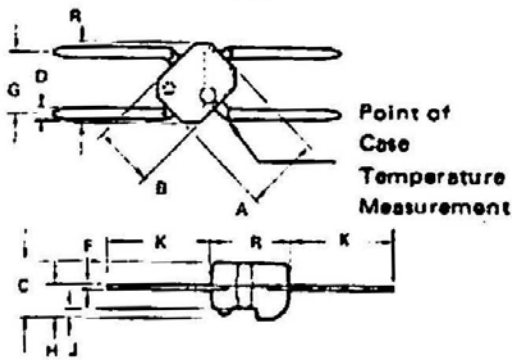


TO-72



| Dim | Inches | | Millimeters | |
|-----|-----------|--------|-------------|--------|
| | Min | Max | Min | Max |
| A | 0.209 | 0.230 | 5.310 | 5.840 |
| B | 0.178 | 0.195 | 4.520 | 4.950 |
| C | 0.170 | 0.210 | 4.320 | 5.330 |
| D | 0.016 | 0.0210 | 0.410 | 0.530 |
| E | - | 0.030 | - | 0.0760 |
| F | 0.016 | 0.0419 | 0.410 | 0.480 |
| G | 0.100 BSC | | 2.540 BSC | |
| H | 0.036 | 0.046 | 0.910 | 1.170 |
| J | 0.028 | 0.048 | 0.710 | 1.220 |
| K | 0.500 | - | 12.700 | - |
| L | 0.250 | - | 6.350 | - |
| M | 45°BSC | | | |
| N | 0.050 BSC | | 1.270 BSC | |
| P | - | 0.050 | - | 1.270 |

3N209



| Dim | Inches | | Millimeters | |
|-----|-----------|-------|-------------|-------|
| | Min | Max | Min | Max |
| A | 0.195 | 0.205 | 4.950 | 5.210 |
| B | 0.155 | 0.165 | 3.940 | 4.190 |
| C | 0.105 | 0.115 | 2.670 | 2.920 |
| D | 0.025 | 0.035 | 0.640 | 0.890 |
| F | 0.008 | 0.012 | 0.200 | 0.300 |
| G | 0.106 BSC | | 4.060 BSC | |
| H | 0.062 | 0.072 | 1.570 | 1.830 |
| J | 0.020 | 0.030 | 0.510 | 0.760 |
| K | 0.250 | 0.300 | 6.350 | 7.620 |
| R | 0.205 | 0.215 | 5.210 | 5.460 |

3N210

Available Non-RoHS (standard) or RoHS compliant (add PBF suffix).
Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add